

## N-CHANNEL SILICON FIELD-EFFECT TRANSISTORS

Asymmetrical N-channel planar epitaxial junction field-effect transistors in the miniature plastic envelope intended for applications up to the v.h.f. range in hybrid thick and thin-film circuits. Special features are the low feedback capacitance and the low noise figure. These features make the product very suitable for applications such as the r.f. stages in f.m. portables (BF510), car radios (BF511) and mains radios (BF512) or the mixer stage (BF513).

### QUICK REFERENCE DATA

Drain-source voltage	$V_{DS}$	max.	20	V		
Drain current (DC or average)	$I_D$	max.	30	mA		
Total power dissipation up to $T_{amb} = 40\text{ }^{\circ}\text{C}$	$P_{tot}$	max.	250	mW		
Drain current			BF510	511	512	513
$V_{DS} = 10\text{ V}; V_{GS} = 0$	$I_{DSS}$	$>$	0.7	2.5	6	10 mA
		$<$	3.0	7.0	12	18 mA
Transfer admittance (common source) $V_{DS} = 10\text{ V}; V_{GS} = 0; f = 1\text{ kHz}$	$ y_{fs} $	$>$	2.5	4	6	7 mS
Feedback capacitance $V_{DS} = 10\text{ V}; V_{GS} = 0$	$C_{rs}$	typ.	0.3	0.3	—	— pF
$V_{DS} = 10\text{ V}; I_D = 5\text{ mA}$	$C_{rs}$	typ.	—	—	0.3	0.3 pF
Noise figure at optimum source admittance $G_S = 1\text{ mS}; -B_S = 3\text{ mS}; f = 100\text{ MHz}$						
$V_{DS} = 10\text{ V}; V_{GS} = 0$	F	typ.	1.5	1.5	—	— dB
$V_{DS} = 10\text{ V}; I_D = 5\text{ mA}$	F	typ.	—	—	1.5	1.5 dB

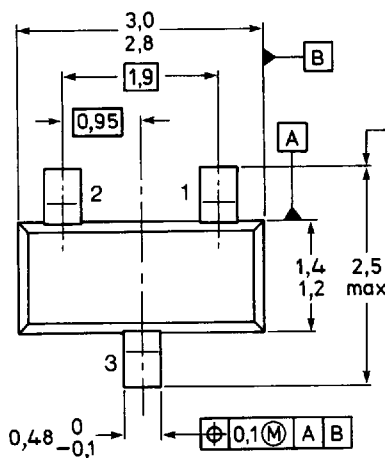
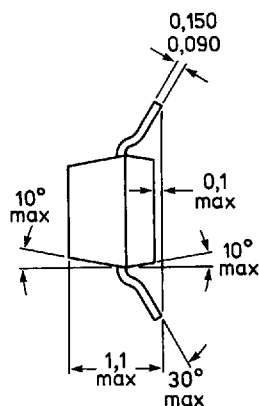
### MECHANICAL DATA

SOT23.

See also *Soldering recommendations*.

# MECHANICAL DATA

Fig. 1 SOT23.



TOP VIEW

Dimensions in mm

## Pinning

- 1 = gate
- 2 = drain
- 3 = source



## Marking code

- BF510 = S6p
- BF511 = S7p
- BF512 = S8p
- BF513 = S9p

7296885

## RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Drain-source voltage	$V_{DS}$	max.	20 V
Drain-gate voltage (open source)	$V_{DGO}$	max.	20 V
Drain current (DC or average)	$I_D$	max.	30 mA
Gate current	$\pm I_G$	max.	10 mA
Total power dissipation up to $T_{amb} = 40^\circ C$ (note 1)	$P_{tot}$	max.	250 mW
Storage temperature range	$T_{stg}$		$-65$ to $+150^\circ C$
Junction temperature	$T_j$	max.	$150^\circ C$

## THERMAL RESISTANCE

From junction to ambient (note 1)

$$R_{th\ j-a} = 430\ K/W$$

## Note

1. Mounted on a ceramic substrate of 8 mm x 10 mm x 0.7 mm.

# STATIC CHARACTERISTICS

$T_{amb} = 25^{\circ}C$

			BF510	511	512	513
Gate cut-off current						
$-V_{GS} = 0.2 V; V_{DS} = 0$	$-I_{GSS}$	<	10	10	10	10 nA
Gate-drain breakdown voltage						
$I_S = 0; -I_D = 10 \mu A$	$-V_{(BR)GDO}$	>	20	20	20	20 V
Drain current						
$V_{DS} = 10 V; V_{GS} = 0$	$I_{DSS}$	>	0.7	2.5	6	10 mA
		<	3.0	7.0	12	18 mA
Gate-source cut-off voltage						
$I_D = 10 \mu A; V_{DS} = 10 V$	$-V_{(P)GS}$	typ.	0.8	1.5	2.2	3 V

# DYNAMIC CHARACTERISTICS

Measuring conditions (common source):  $V_{DS} = 10 V; V_{GS} = 0; T_{amb} = 25^{\circ}C$  for BF510 and BF511  
 $V_{DS} = 10 V; I_D = 5 mA; T_{amb} = 25^{\circ}C$  for BF512 and BF513

y-parameters (common source)			BF510	511	512	513
Input capacitance at $f = 1 MHz$	$C_{is}$	<	5	5	5	5 pF
Input conductance at $f = 100 MHz$	$g_{is}$	typ.	100	90	60	50 $\mu S$
Feedback capacitance at $f = 1 MHz$	$C_{rs}$	typ.	0.3	0.3	0.3	0.3 pF
		<	0.4	0.4	0.4	0.4 pF
Transfer admittance at $f = 1 kHz$	$ y_{fs} $	>	2.5	4.0	4.0	3.5 mS
$V_{GS} = 0$ instead of $I_D = 5 mA$	$ y_{fs} $	>	—	—	6.0	7.0 mS
Transfer admittance at $f = 100 MHz$	$ y_{fs} $	typ.	3.5	5.5	5.0	5.0 mS
Output capacitance at $f = 1 MHz$	$C_{os}$	<	3	3	3	3 pF
Output conductance at $f = 1 MHz$	$g_{os}$	<	60	80	100	120 $\mu S$
Output conductance at $f = 100 MHz$	$g_{os}$	typ.	35	55	70	90 $\mu S$
Noise figure at optimum source admittance						
$G_S = 1 mS; -B_S = 3 mS;$						
$f = 100 MHz$	F	typ.	1.5	1.5	1.5	1.5 dB

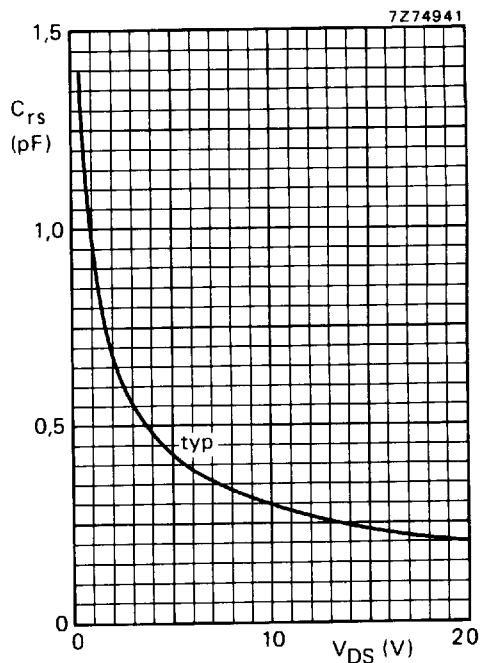


Fig. 2  $V_{GS} = 0$  for BF510 and BF511;  
 $I_D = 5$  mA for BF512 and BF513;  
 $f = 1$  MHz;  $T_{amb} = 25$  °C.

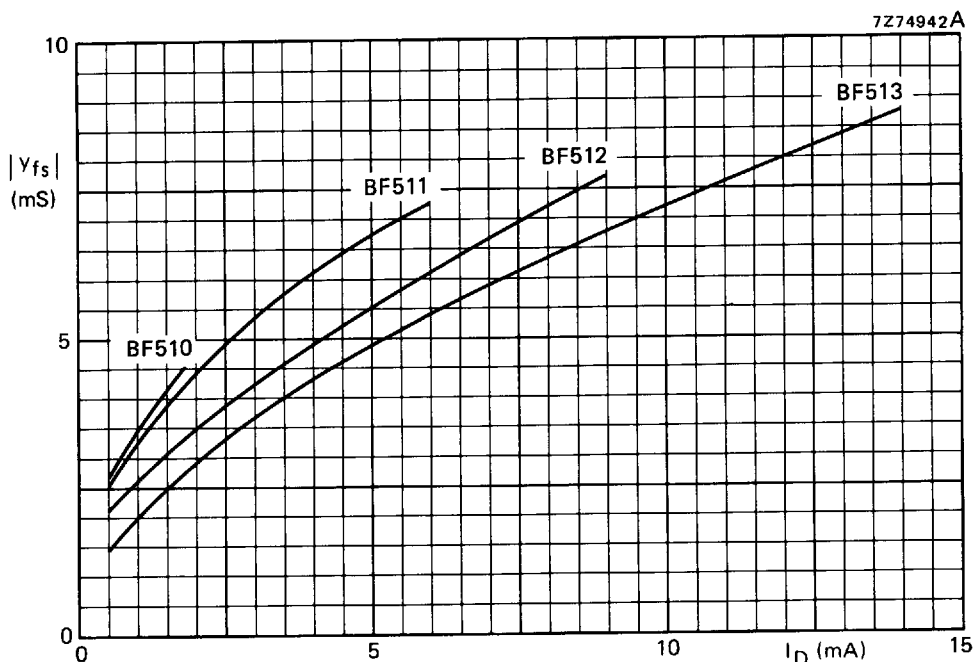


Fig. 3  $V_{DS} = 10$  V;  $f = 1$  kHz;  $T_{amb} = 25$  °C; typical values.

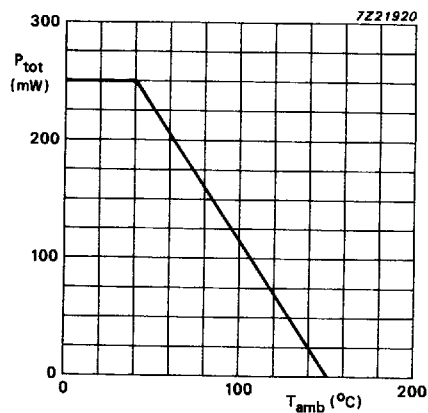


Fig.4 Power derating curve.